

Qualcomm[®] Automotive Powerline Communication (PLC) Solutions

Qualcomm Automotive Powerline Communication Solutions



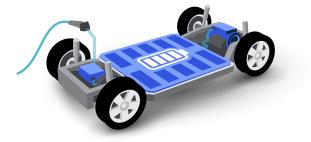
Robust. Reliable. Energy-efficient.

According to analysis from Deloitte¹, electric vehicles (EVs) will be a third of all new car sales by 2030, bringing the total number of EVs sold in a single year to 31.1 million globally—10 million more than previously forecasted. To meet this growing demand, global automakers and suppliers turn to Qualcomm Technologies: a leading PLC HPGP device supplier for Combined Charging System (CCS) EVs, infrastructure, and accessories. We provide a wide range of PLC HPGP devices that fully fit CCS standard requirements, which is the leading global standard for automotive DC charging. Our PLC HPGP solutions are used for several defined applications worldwide, including vehicles, smart grid infrastructure, public charging stations, in-home charger units, EV accessories, and adapters.

PLC HPGP use cases for Automotive & Smart Grid applications

Compelling solution to enable an integrated EV + Smart Grid Ecosystem

On-Board Conductive Charging systems (OBCs)

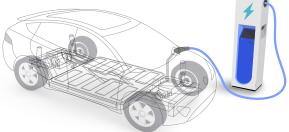


Converters, accessories & smart/solar home applications (often tied with EV @ home charging)





Off Board Conductive Charging systems (EVSEs, Home Chargers)



Bi-directional V2H & V2G communication



VIG: Unidirectional controlled charging Vehicles or charging infrastructure adjust their rate of charging V2G: Vehicle-to-grid Smart grid controls vehicle charging and returns electricity to the grid V2H/B: Vehicle-to-home/-building Vehicles will act as supplement power suppliers to the home

Benefits of PLC HPGP Charging Applications (CCS)

- Developed and matured over the last 10 years by leading automotive and infrastructure providers
- PLC HPGP-based communication supports smart-grid applications
- CharlN leading the charge to establish CCS as a preferred worldwide EV charging solution
- Strong supply base with multiple device manufacturers committed to the market

Qualcomm PLC HPGP solutions

	QCA7000-AL3C	QCA7000-AL3B	QCA7005-AL33	QCA70106AQ
Direction	HPGP single chip MAC/PHY	HPGP single chip MAC/PHY	HPGP single chip MAC/PHY	HPGP single chip MAC/PHY HPAV single chip MAC/PHY
Digital Interfaces	SPI	SPI	SPI	SPI, Ethernet
Quality Level	Commercial	Industrial	Enhanced Industrial*	Automotive Grade 2
Operating Ambient Temp. Range	0°C to +70°C	-40°C to +85°C	-40°C to +85°C	-40°C to +105°C
Case Temperature	0°C to +105°C	-40°C to +110°C	-40°C to +110°C	-40°C to +110°C
Package	QFN68 0.4mm pin pitch	QFN68 0.4mm pin pitch	QFN68 0.4mm pin pitch with wettable flanks	QFN68 0.4mm pin pitch with wettable flanks

- PLC HPGP modem device compliant with PLC HPGP MAC/PHY specifications
- QoS as required for PLC HPGP home area network
- Robust, reliable, and power-efficient networking solution as per PLC HPGP specs
- Minimum bill of material (BOM) to enable PLC HPGP communication

New QCA7006AQ

All-in-one, automotive-grade PLC HPGP solution

SPI Interface Slave	ARM Processor	ROM	RAM
GPIOs	Memory Ctrl (DN	Power Management Unit	
ETH PHY Tx/Rx Interface	HPGP MAC/PHY Engine	HPAV MAC/PHY Engine	Switching Voltage Regulator
Analog Front-end (AFE) ADC DAC RF Transceiver		XTAL Oscillator	SPI Interface Master (for ext memory)

Operational overview

Compliant with both HPGP and HPAV specifications

Compliant with ISO 15118 (part 1, part 2, part 3) specifications

Fully interoperable with IEEE 1901 family specifications

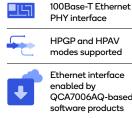
Meets CCS type 1 and type 2 requirements

Note: Size of depicted blocks is not indication of silicon size of IP cells.

Key value-adds







Ethernet interface QCA7006AQ-based software products



Digital interface (ETH, SPI) configurable through **PIB** configuration file

QCA7006AQ

- Seamless upgrade from QCA7000/QCA7005 to QCA7006AQ
- Footprint and pinout compatibility with QCA7000 and QCA7005 devices
- Interoperable with QCA7000 and QCA7005 devices
- Operational with QCA7006AQ-based software products ٠

Qualcomm Automotive PLC Communication advantages



Innovation & Experience

- · 20+ years of automotive industry experience
- 150+ million vehicles using Qualcomm Automotive solutions
- #1 in telematics, Bluetooth, and Wi-Fi for Automotive
- #1 in premium, next-gen cockpit design wins for production vehicles starting 2020



PLC Leadership

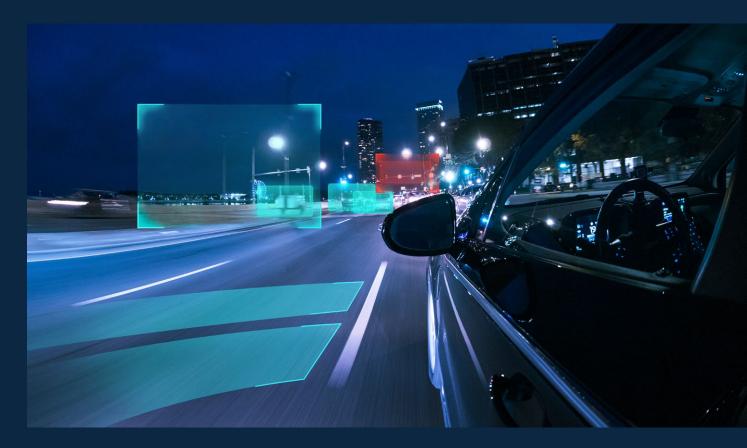
- · Leading PLC device supplier for the CCS EV, Infrastructure, and Accessories markets
- · Large market share driven by 10+ years in EV segment
- Stable HW platform and mature HPGP SW for CCS applications



OEM & Governmental Support

- Most EV OEMs use QC700X devices
- Government agencies—such as the California Energy Commission—are actively driving the build out of CCS-enabled EVSE infrastructure from 2022 to 2030 to accelerate EV adoption and smart grid integration.

Qualcomm



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